

## General Description

MOSFET Power Module provides very low  $R_{DS(on)}$  as well as optimized intrinsic diode. It's designed for the applications such as hybrid and electric vehicle.

## Features

- SiC power MOSFET
- Low  $R_{DS(on)}$
- Optimized intrinsic reverse diode
- Low inductance case avoid oscillations
- Isolated copper pinfin baseplate using  $\text{Si}_3\text{N}_4$  DBC technology

## Typical Applications

- Automotive application
- Hybrid and electric vehicle
- Inverter for motor drive

## Absolute Maximum Ratings $T_F=25^\circ\text{C}$ unless otherwise noted

Symbol	Description	Value	Unit
$V_{DSS}$	Drain-Source Voltage	1200	V
$V_{GSSmax}$	Gate-Source Voltage	-6/+20	V
$V_{GSSop}$	Gate-Source Voltage	-4/+15,18	V
$I_D$	Drain Current @ $T_F=75^\circ\text{C}$	420	A
$I_{DM}$	Pulsed Drain Current, $t_P$ limited by $T_{jmax}$	2040	A
$P_D$	Maximum Power Dissipation @ $T_F=75^\circ\text{C}$ $T_j=175^\circ\text{C}$	787	W

## Body Diode

Symbol	Description	Value	Unit
$I_{SN}$	Implemented Source Current	420	A
$I_S$	Source Current @ $T_F=75^\circ\text{C}$	420	A
$I_{SM}$	Pulsed Source Current, $t_P$ limited by $T_{jmax}$	840	A

## Module

Symbol	Description	Value	Unit
$T_{jmax}$	Maximum Junction Temperature	175	$^\circ\text{C}$
$T_{jop}$	Operating Junction Temperature	-40 to +150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-40 to +125	$^\circ\text{C}$
$V_{ISO}$	Isolation Voltage RMS,f=50Hz,t=5s	4000	V

**MOSFET Characteristics**  $T_F=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	Static Drain-Source On-Resistance	$I_D=420\text{A}, V_{GS}=15\text{V}, T_j=25^\circ\text{C}$		2.21	2.71	$\text{m}\Omega$
		$I_D=420\text{A}, V_{GS}=15\text{V}, T_j=150^\circ\text{C}$		4.29		
$V_{GS(th)}$	Gate-Source Threshold	$I_D=211\text{mA}, V_{DS}=10\text{V}, T_j=25^\circ\text{C}$	1.5	-	4.5	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=V_{DSS}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$			600	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=-6/+15\text{V}, V_{DS}=0\text{V}, T_j=25^\circ\text{C}$			600	nA
$R_{Gint}$	Internal GateResistance				1.0	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=800\text{V}, f=1\text{MHz}$		44.6		nF
$C_{oss}$	Output Capacitance			1.07		nF
$C_{rss}$	Reverse Transfer Capacitance			0.11		nF
$Q_g$	Total Gate Charge	$I_D=420\text{A}, V_{DS}=600\text{V}, V_{GS}=15\text{V}$		1440		nC
$Q_{gs}$	Gate-Source Charge			400		nC
$Q_{gd}$	Gate-Drain ("Miller") Charge			400		nC
$E_{on}$	Turn-On Switching Loss	$V_{DS}=600\text{V}, I_D=420\text{A}, R_G=0\Omega, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$		19.5		mJ
$E_{off}$	Turn-Off Switching Loss			17.6		mJ

**Body Diode Characteristics**  $T_F=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{SD}$	Diode Forward Voltage	$I_S=150\text{A}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$		2.1		V
		$I_S=120\text{A}, V_{GS}=0\text{V}, T_j=150^\circ\text{C}$		2.9		
$t_{rr}$	Diode Reverse Recovery Time	$V_R=600\text{V}, I_S=420\text{A}, -di/dt=TBDA/\mu\text{s}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$		30		ns
$Q_r$	Diode Reverse Recovery Charge			11.5		$\mu\text{C}$
$E_{rec}$	Reverse Recovery Energy			0.9		mJ

# LSM22H120P6B1

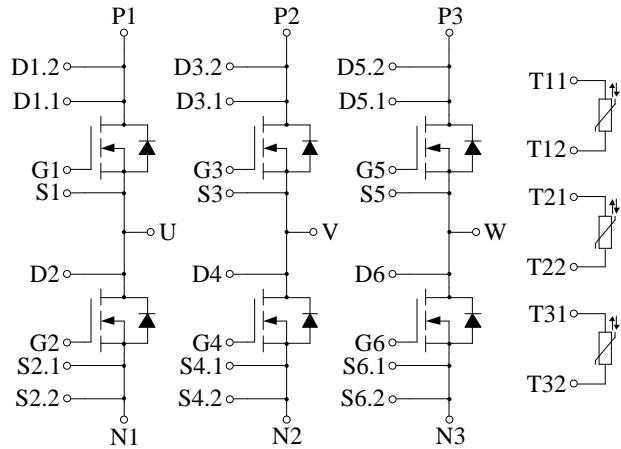
## **NTC Characteristics** $T_F=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{25}$	Rated Resistance			5.0		$\text{k}\Omega$
$\Delta R/R$	Deviation of $R_{100}$	$T_j = 100^\circ\text{C}, R_{100} = 493.3\Omega$	-5		5	%
$P_{25}$	Power Dissipation				20.0	$\text{mW}$
$B_{25/50}$	B-value	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298.15\text{K}))]$		3365		K
$B_{25/80}$	B-value	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298.15\text{K}))]$		3442		K
$B_{25/100}$	B-value	$R_2 = R_{25} \exp[B_{25/100}(1/T_2 - 1/(298.15\text{K}))]$		3426		K

## **Module Characteristics** $T_F=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
$L_{CE}$	Stray Inductance		8		$\text{nH}$
$R_{CC+EE}$	Module Lead Resistance, Terminal to Chip		0.75		$\text{m}\Omega$
$\Delta p$	$\Delta V/\Delta t = 10.0 \text{dm}^3/\text{min}, T_F = 75^\circ\text{C}$		64		$\text{mbar}$
p	Maximum Pressure In Cooling Circuit			2.5	bar
$R_{thJF}$	Junction-to-Cooling Fluid (per MOSFET) $\Delta V/\Delta t = 10.0 \text{dm}^3/\text{min}, T_F = 75^\circ\text{C}$			0.127	K/W
M	Terminal Connection Torque, Screw M5 Mounting Torque, Screw M4	3.6 1.8		4.4 2.2	N.m
G	Weight of Module		750		g

## Circuit Schematic



## Package Dimensions

Dimensions in Millimeters

